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New Cover Lids for Electronics Enclosures From Pixus Technologies Snap On Easily

Waterloo, Ontario — Jan 30, 2018 – Pixus Technologies, a provider of embedded computing and enclosure solutions, now offers covers for instrumentation enclosures with snap-on lids for easy assembly.

The new Pixus enclosure lids feature a side edge fold with half shears that allow a solid or perforated enclosure cover to snap into place. The covers have side notches for fitting into rails with 160mm, 280mm or 280mm depths. This lid design provides easy and cost-effective assembly. EMC gaskets are also included. The snap-on lids are available for Pixus' Vario, RiCase, Mobile, and EMC subrack enclosure systems.

Pixus provides subracks and electronics enclosures for various applications, including Industrial, Energy, Communications, Mil/Aero, Medical, Transportation, Research/Physics, and other markets. The company also provides backplanes, chassis platforms, and components for embedded computing systems.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.